



Product Change Notification

Change Notification #: 117029 - 00
Change Title: Intel® Server System H2312XXKR2 PCN 117029-00, Label, BSMI label update
Date of Publication: June 26, 2019

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

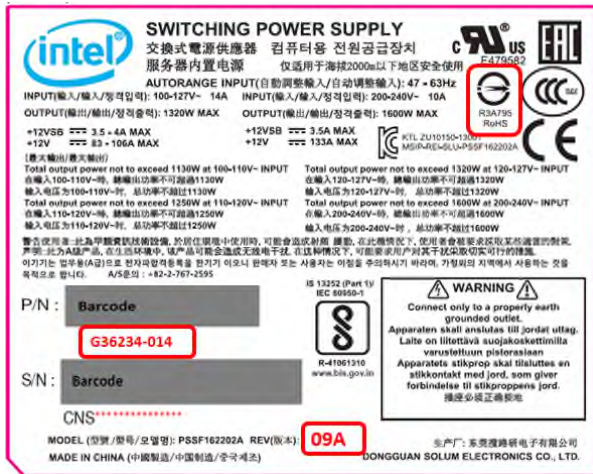
Date Customer Must be Ready to Receive Post-Conversion Material: *	July 11, 2019
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

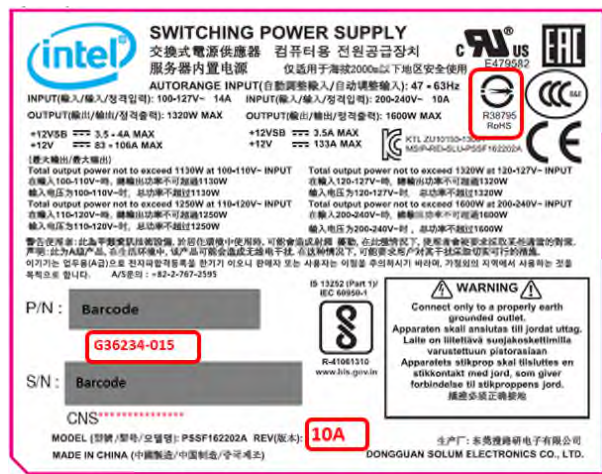
Description of Change to the Customer:

Intel is updating the BSMI RoHS certificate label of server system H2312XXKR2 to comply with certificate mark. Additionally, the power supply FW version will be updated from 76.9.128 to 77.9.128 only to reflect label update.

BSMI Label before (changes in red):



BSMI Label after (changes in red):



Packing label before (changes in red)

Part No	#1	G36234-014
Lot No	#2	SE381840
Qty	#3	8PC # Rev 09A
Date	#5	2018.10.04
User	#6	INTEL
Model	#7	PSSF162202A
Remark	#8	B11Q8U015

B11Q8U01500200

Packing label after (changes in red)

Part No	#1	G36234-015
Lot No	#2	SE381840
Qty	#3	8PC # Rev 10A
Date	#5	2018.10.04
User	#6	INTEL
Model	#7	PSSF162202A
Remark	#8	B11Q8U015

B11Q8U01500200

Inner box label before (Single Package Unit)

#1	PRODUCT : FXX1600PCRPS	#7	QTY : 1
#2	VERSION # : G44214-007	#6	MM# : 915606
#3	SERIAL # : CNS1622A4SHAO0001	#8	CARTON # : CNEJYMDXXX
#4	UPC CODE : 735858243650	#9	BATCH # : CNEJYMD7SS
#5	EAN CODE : 5032037038294	#10	PACK DATE : DD MMM YY
#11	MADE IN CHINA	#12	ASSEMBLY DESCRIPTION QTY
			G36234-014 PS, ASSY, 1600W, 2, 12, PFC, ERP, 1

Inner box label after (Single Package Unit)

#1	PRODUCT : FXX1600PCRPS	#7	QTY : 1
#2	VERSION # : G44214-008	#6	MM# : 915606
#3	SERIAL # : CNS1622A4SHAO0001	#8	CARTON # : CNEJYMDXXX
#4	UPC CODE : 735858243650	#9	BATCH # : CNEJYMD8SS
#5	EAN CODE : 5032037038294	#10	PACK DATE : DD MMM YY
#11	MADE IN CHINA	#12	ASSEMBLY DESCRIPTION QTY
			G36234-015 PS, ASSY, 1600W, 2, 12, PFC, ERP, 1

Packing label before (changes in red)

#1	PRODUCT : FXX1600PCRPS	#3	MM# : 915606	#4	QTY : 5
#2	VERSION # : G44214-007	#5	BATCH # : CNEJYMD7SS	#6	PACK DATE : DD MMM YY
#7	MADE IN CHINA	#8	UPC CODE	#9	EAN CODE
#10	CARTON # : CNEJYMDXXX	#11	UPC CODE		

Packing label after (changes in red)

#1	PRODUCT : FXX1600PCRPS	#3	MM# : 915606	#4	QTY : 5
#2	VERSION # : G44214-008	#5	BATCH # : CNEJYMD8SS	#6	PACK DATE : DD MMM YY
#7	MADE IN CHINA	#8	UPC CODE	#9	EAN CODE
#10	CARTON # : CNEJYMDXXX	#11	UPC CODE		

Customer Impact of Change and Recommended Action:

Intel does not expect any other impact to customers from these changes but encourages customers to understand the change and determine the impact on their applications.

Therefore Intel recommends that the customer perform a standard level of evaluation. Latest BIOS/ME/Integrated BMC and FRUSDR packages and release notes can be download from <http://www.intel.com/support>.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
H2312XXKR2	933689	H20865-017	H20865-018

PCN Revision History:

Date of Revision:

June 26, 2019

Revision Number:

00

Reason:

Originally Published PCN



Product Change Notification

117029 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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